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December 2013

FPDB40PH60B PFC SPM[®] 3 Series for 2-Phase Bridgeless PFC

Features

- UL Certified No. E209204 (UL1557)
- 600 V 40 A 2-Phase Bridgeless PFC with Integral Gate Driver and Protection
- Very Low Thermal Resistance Using Al₂O₃ DBC Substrate
- · Built-in NTC Thermistor for Temperature Monitoring
- · Built-in Shunt Resistor for Current Sensing
- · Optimized for 20kHz Switching Frequency
- · Isolation Rating: 2500 Vrms/min.

Applications

• 2-Phase Bridgeless PFC Converter

Related Source

• <u>AN-9041 - Bridgeless PFC SPM 3 Series Design</u> <u>Guide</u>

General Description

The FPDB40PH60B is an advanced PFC SPM® 3 module providing a fully-featured, high-performance Bridgeless PFC (Power Factor Correction) input power stage for consumer, medical, and industrial applications. These modules integrate optimized gate drive of the built-in IGBTs to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockout, over-current shutdown, thermal monitoring, and fault reporting. These modules also feature high-performance output diodes and shunt resistor for additional space savings and mounting convenience.

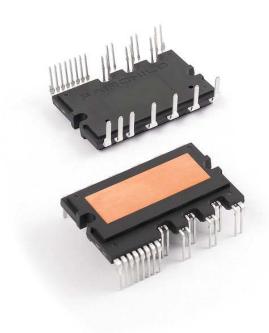


Figure 1. Package Overview

Package Marking & Ordering Information

Device	Device Marking	Package	Packing Type	Quantity
FPDB40PH60B	FPDB40PH60B	SPMGC-027	Rail	10

Integrated Drive, Protection and System Control Functions

- For IGBTs: gate drive circuit, Over-Current Protection (OCP), control supply circuit Under-Voltage Lock-Out (UVLO) Protection
- · Fault signal: corresponding to OC and UV fault
- · Built-in thermistor: temperature monitoring
- Input interface: active-HIGH interface, works with 3.3 / 5 V logic, Schmitt-trigger input

Pin Configuration

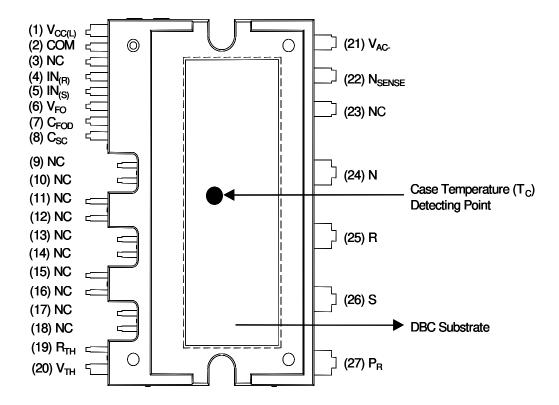


Figure 2. Top View

Pin Descriptions

Pin Number	Pin Name	Pin Description	
1	V _{CC}	Common Bias Voltage for IC and IGBTs Driving	
2	COM	Common Supply Ground	
4	IN _(R)	Signal Input for Low-Side R-Phase IGBT	
5	IN _(S)	Signal Input for Low-Side S-Phase IGBT	
6	V _{FO}	Fault Output	
7	C _{FOD}	Capacitor for Fault Output Duration Selection	
8	C _{SC}	Capacitor(Low-Pass Filter) for Over-Current Detection	
19	R _(TH)	Series Resistor for The Use of Thermistor	
20	V _(TH)	Thermistor Bias Voltage	
21	V _{AC-}	Current Sensing Terminal	
22 N _{SENSE} Current Sensing Reference Terminal		Current Sensing Reference Terminal	
24	N	Negative Rail of DC-Link	
25	R	Output for R-Phase	
26	S	Output for S-Phase	
27	P _R	Positive Rail of DC-Link	
3, 9~18, 23	NC	No Connection	

Internal Equivalent Circuit

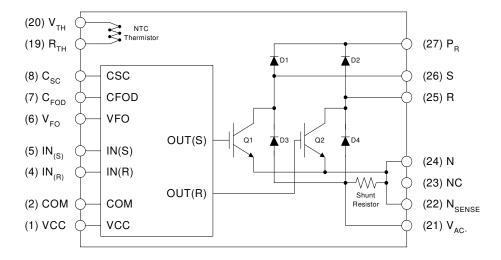


Figure 3. Internal Block Diagram

Notes:

1. Converter is composed of two IGBTs including four diodes and one IC which has gate driving and protection functions.

Absolute Maximum Ratings ($T_J = 25$ °C, unless otherwise specified.) **Converter Part**

Symbol	Item	Condition	Rating	Unit
V _i	Supply Voltage	Applied between R - S	264	V _{rms}
V _{i(Surge)}	Supply Voltage (Surge)	Applied between R - S	500	V
V_{PN}	Output Voltage	Applied between P - N	450	V
V _{PN(Surge)}	Output Voltage (Surge)	Applied between P - N	500	V
V _{CES}	Collector - Emitter Voltage		600	V
±Ι _C	Each IGBT Collector Current	T _C = 25°C	40	Α
±I _{CP}	Each IGBT Collector Current (Peak)	T _C = 25°C, Under 1 ms Pulse Width	70	Α
P _C	Collector Dissipation	T _C = 25°C per IGBT	113	W
V _{RRM}	Repetitive Peak Reverse Voltage		600	V
I _{FSM}	Peak Forward Surge Current	Single Half Sine-Wave	350	Α
P _{RSH}	Power Rating of Shunt Resistor	T _C < 125°C	2	W
T _J	Operating Junction Temperature	(Note 2)	-40 ~ 150	°C

Notes

Control Part

Symbol	Item	Condition	Rating	Unit
V _{CC}	Control Supply Voltage	Applied between V _{CC} - COM	20	V
V _{IN}	Input Signal Voltage	Applied between IN - COM	-0.3 ~ 17.0	٧
V _{FO}	Fault Output Supply Voltage	Applied between V _{FO} - COM	-0.3 ~ V _{CC} +0.3	V
I _{FO}	Fault Output Current	Sink Current at V _{FO} Pin	5	mA
V _{SC}	Current Sensing Input Voltage	Applied between C _{SC} - COM	-0.3~V _{CC} +0.3	٧

Total System

Symbol	Item	Condition	Rating	Unit
T _C	Module Case Operation Temperature		-20 ~ 100	ô
T _{STG}	Storage Temperature		-40 ~ 150	°Ç
V _{ISO}	Isolation Voltage	60 Hz, Sinusoidal, AC 1 Minute, Connect Pins to Heat-Sink Plate	2500	V _{rms}

Thermal Resistance

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
$R_{\theta(j\text{-c})Q}$	Junction to Case Thermal Resistance	IGBT	-	-	1.1	°C/W
$R_{\theta(j-c)HD}$	(Referenced to PKG Center)	High-Side Diode	-	-	1.9	°C/W
$R_{\theta(j-c)LD}$		Low-Side Diode	-	-	1.4	°C/W

Notes

^{2.} The maximum junction temperature rating of the power chips integrated within the PFC SPM[®] product is 150° C(@T_C $\leq 100^{\circ}$ C).

^{3.} For the measurement point of case temperature($T_{\mbox{\scriptsize C}}$), please refer to Figure 2.

$\textbf{Electrical Characteristics} \ \, (\text{T}_{\text{J}} = 25^{\circ}\text{C}, \text{ unless otherwise specified.})$

Converter Part

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
V _{CE(SAT)}	IGBT Saturation Voltage	V _{CC} = 15 V, V _{IN} = 5 V, I _C = 40 A	-	1.8	2.3	٧
V_{FH}	High-Side Diode Voltage	I _F = 40 A	-	2.2	2.7	٧
V_{FL}	Low-Side Diode Voltage	I _F = 40 A	-	1.15	1.55	٧
t _{ON}	Switching Times	V _{PN} = 400 V, V _{CC} = 15 V, I _C = 40 A	-	500	-	ns
t _{C(ON)}		$V_{IN} = 0 \text{ V} \leftrightarrow 5 \text{ V}$, Inductive Load	-	180	-	ns
t _{OFF}		(Note 4)	-	500	-	ns
t _{C(OFF)}			-	90	-	ns
t _{rr}			-	43	-	ns
I _{rr}			-	6	-	Α
R _{SENSE}	Current-Sensing resistor		1.8	2.0	2.2	mΩ
I _{CES}	Collector - Emitter Leakage Current	V _{CE} = V _{CES}	-	-	250	μА

Notes:
4. t_{ON} and t_{OFF} include the propagation delay of the internal drive IC. t_{C(ON)} and t_{C(OFF)} are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

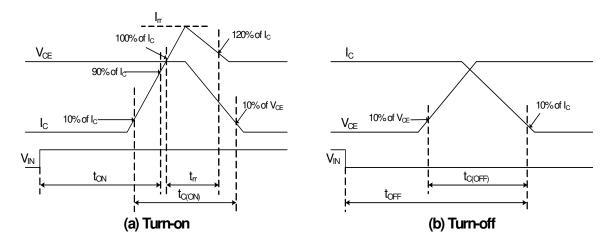


Figure 4. Switching Time Definition

Control Part

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
I _{QCCL}	Quiescent V _{CC} Supply Current	V _{CC} = 15 V, IN = 0 V V _{CC} - COM	-	1	26	mA
V_{FOH}	Fault Output Voltage	V_{SC} = 0 V, V_{FO} Circuit: 4.7 k Ω to 5 V Pull-up	4.5	-	-	V
V _{FOL}		V_{SC} = 1 V, V_{FO} Circuit: 4.7 k Ω to 5 V Pull-up	-	-	0.8	V
V _{SC(ref)}	Over-Current Trip Level	V _{CC} = 15 V	0.45	0.50	0.55	V
UV _{CCD}	Supply Circuit Under-Voltage	Detection Level	10.7	11.9	13.0	V
UV _{CCR}	Protection	Reset Level	11.2	12.4	13.2	V
t _{FOD}	Fault-Out Pulse Width	C _{FOD} = 33 nF (Note 5)		1.8	2.0	ms
V _{IN(ON)}	ON Threshold Voltage	Applied between IN - COM	3.0	-	-	V
V _{IN(OFF)}	OFF Threshold Voltage		-	-	0.8	V
R _{TH}	Resistance of Thermistor	at T _C = 25°C (See Figure 5)	-	50	-	kΩ
		at T _C = 80°C (See Figure 5)	-	5.76	-	kΩ

Notes:
5. The fault-out pulse width t_{FOD} depends on the capacitance value of C_{FOD} according to the following approximate equation: $C_{FOD} = 18.3 \times 10^{-6} \times t_{FOD}[F]$



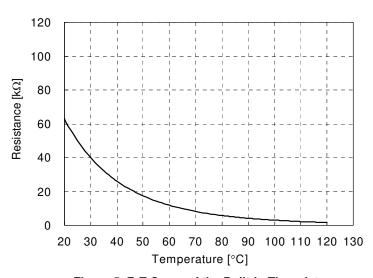


Figure 5. R-T Curve of the Built-in Thermistor

Recommended Operating conditions

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
V _I	Input Supply Voltage	Applied between R - S	180	-	264	V _{rms}
V _{PN}	Output Voltage	Applied between P - N	-	280	400	٧
V _{CC}	Control Supply Voltage	Applied between V _{CC} - COM	13.5	15	16.5	٧
dV _{CC} /dt	Control Supply Variation	Applied between IN - COM	-1	-	1	V/µs
f _{PWM}	PWM Input Signal	T _C ≤ 100°C, T _J ≤ 125°C, per IGBT	-	20	-	kHz

Mechanical Characteristics and Ratings

Item	Co	ndition	Min.	Тур.	Max.	Units
Mounting Torque	Mounting Screw: M3	Recommended 0.62 N•m	0.51	0.62	0.72	N•m
Device Flatness	See Figure 6		0	-	+120	μm
Weight			-	15.00	-	g

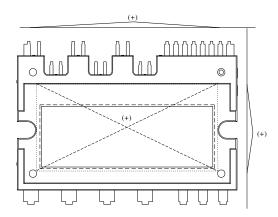
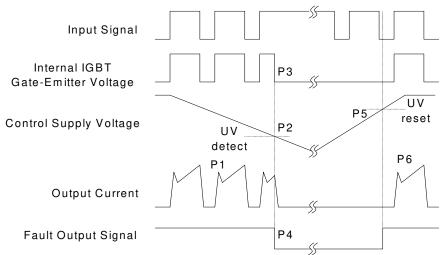


Figure 6. Flatness Measurement Position

Time Charts of Protective Function

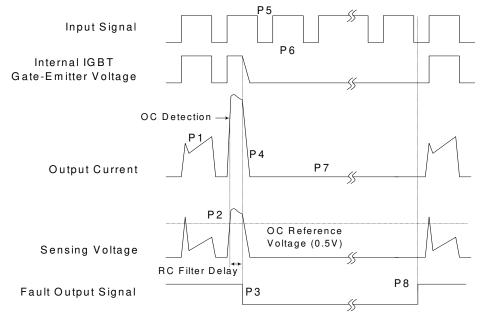


P1: Normal operation: IGBT ON and conducting current.

P2: Under-voltage detection.
P3: IGBT gate interrupt.
P4: Fault signal generation.
P5: Under-voltage reset.

P6: Normal operation: IGBT ON and conducting current.

Figure 7. Under-Voltage Protection



P1: Normal operation: IGBT ON and conducting current.

P2 : Over current detection.

P3: IGBT gate interrupt / fault signal generation.

P4: IGBT is slowly turned off.

P5: IGBT OFF signal.

P6 : IGBT ON signal: but IGBT cannot be turned on during the fault output activation.

P7: IGBT OFF state.

P8 : Fault output reset and normal operation start.

Figure 8. Over-Current Protection

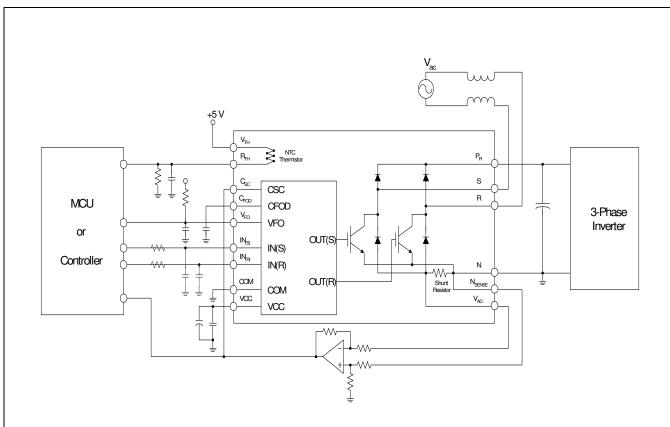
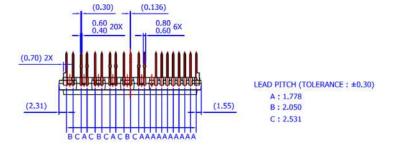
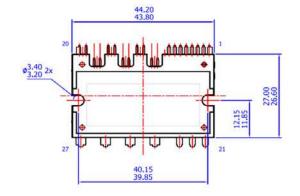


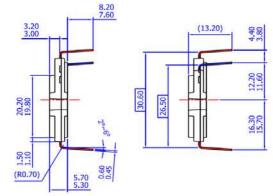
Figure 9. Application Example

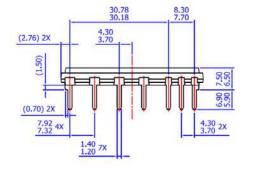
Notes: 6. For the over-current protection, please set time constant in the range $~3\sim 4~\mu s.$

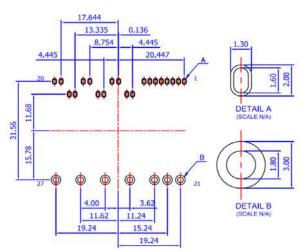
Detailed Package Outline Drawings











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